

Description

The STD6NF10T4 uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =100V,I_D =15A

 $R_{DS(ON)}$ <112m Ω @ V_{GS} =10V

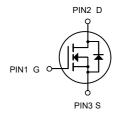
Application

Power switch

DC/DC converters



TO-252-2L (DPAK)



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
STD6NF10T	TO-252-2L(DPAK)	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	100	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	GS @ 10V ¹ 7.7		
Ірм	Pulsed Drain Current ²	24	А	
EAS	Single Pulse Avalanche Energy ³	6.1	mJ	
las	Avalanche Current	11	А	
P _D @T _C =25°C	Total Power Dissipation ³	34.7	W	
Тѕтѕ	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
Reja	Thermal Resistance Junction-ambient ¹	62 °C		
Rejc	Thermal Resistance Junction-Case ¹	3.6 °C/W		



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V	
△BV _{DSS} /△T _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA		0.098		V/°C	
_	0.1. 0.1. 0. 0. 0. 0. 1. 1. 2.	V _{GS} =10V , I _D =10A		100	112	mΩ	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =8A		117	130	mΩ	
VGS(th)	Gate Threshold Voltage		1.0		2.5	V	
		V _{GS} =V _{DS} , I _D =250uA					
$\triangle V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient			-4.57		mV/°C	
		V _{DS} =80V , V _{GS} =0V , T _J =25°C			1		
loss	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55°C			5	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =10A		13		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2		Ω	
Qg	Total Gate Charge (10V)			26.2			
Qgs	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =10A		4.6		nC	
Qgd	Gate-Drain Charge			5.1			
Td(on)	Turn-On Delay Time			4.2			
Tr	Rise Time	V_{DD} =50V , V_{GS} =10V , R_{G} =3.3 Ω		8.2		ns	
Td(off)	Turn-Off Delay Time	I _D =10A		35.6			
Tf	Fall Time			9.6			
Ciss	Input Capacitance			1535			
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		60		pF	
Crss	Reverse Transfer Capacitance			37			
ls	Continuous Source Current ^{1,5}				12	Α	
lsм	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			24	Α	
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	
trr	Reverse Recovery Time	I- 40A III 400A /		37		nS	
Qrr	Reverse Recovery Charge	IF=10A, dI/dt=100A/μs, T _J =25°C		27.3		nC	

^{1.} The data tested by surface mounted on a 1 inch $_2\,FR$ -4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$

 $^{3.} The \ EAS \ data \ shows \ Max. \ rating \ . \ The \ test \ condition \ is \ V_{DD}=25V, V_{GS}=10V, L=0.1 mH, I_{AS}=11A$

^{4.}The power dissipation is limited by 150°C junction temperature

^{5.}The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.



Typical Characteristics

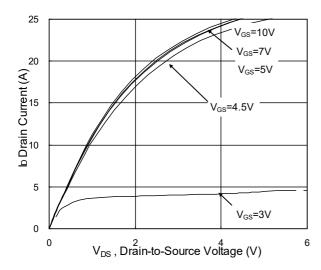


Fig.1 Typical Output Characteristics

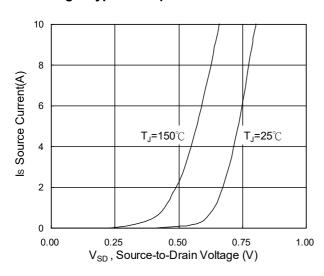


Fig.3 Forward Characteristics Of Reverse

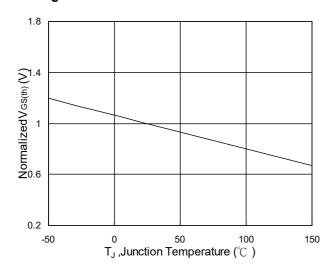


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

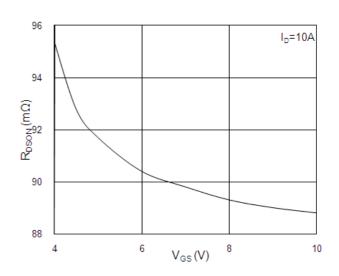


Fig.2 On-Resistance vs. Gate-Source

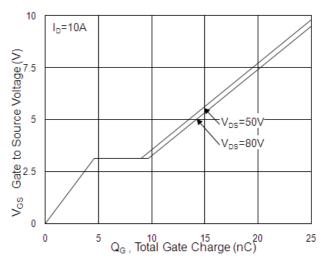


Fig.4 Gate-Charge Characteristics

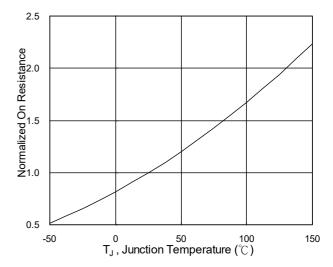
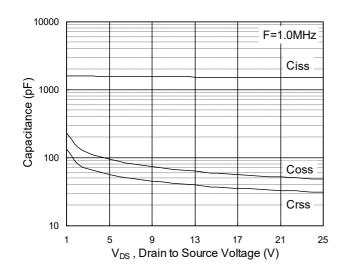


Fig.6 Normalized R_{DSON} vs. T_J



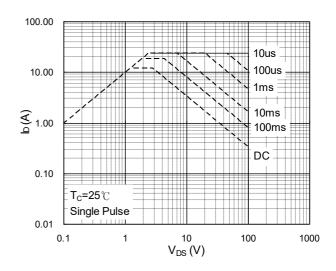


Fig.7 Capacitance

Fig.8 Safe Operating Area

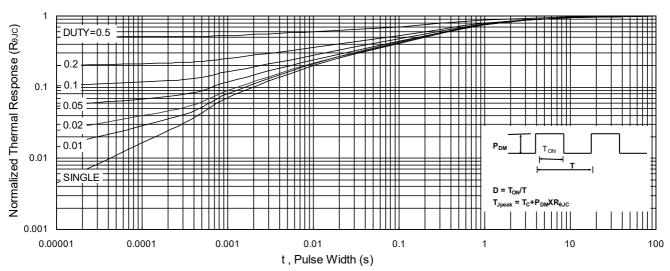


Fig.9 Normalized Maximum Transient Thermal Impedance

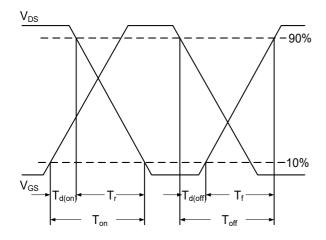


Fig.10 Switching Time Waveform

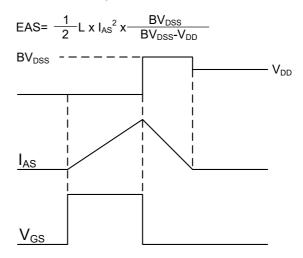
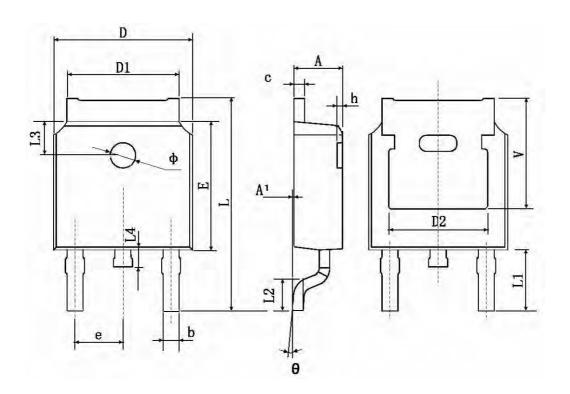


Fig.11 Unclamped Inductive Switching Waveform

TO-252-2L(DPAK) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production.

 HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc.

 When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.